




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-07-15
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement				
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Legal Statement				
Supplier Acceptance *	<table style="width: 100%; border: none;"> <tr> <td style="width: 33%; text-align: center;">true</td> <td style="width: 33%; text-align: center;">Legal Declaration *</td> <td style="width: 33%; text-align: center;">Standard</td> </tr> </table>	true	Legal Declaration *	Standard
true	Legal Declaration *	Standard		
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>			

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
X0202MN 5BA4	EGLM*X0203TS	A	Z4XA	2016-07-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	110.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3.5 - 6.5 - 1.8	4	gull wing	
Comment	Package: SOT 223 PLANAR and TOPGLASS			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EGLM*X0203TS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.106	mg	supplier	die	Silicon (Si)	7440-21-3		0.922	mg	833635	8382
				supplier	metallization	Nickel (Ni)	7440-02-0		0.075	mg	67812	682
				supplier	metallization	Gold (Au)	7440-57-5		0.008	mg	7233	73
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.005	mg	4522	45
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1808	18
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.008	mg	7233	73
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.009	mg	8137	82
				JIG - R	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	0.077	mg	69620	700
Leadframe	Copper & its alloys	52.256	mg	supplier	alloy	Copper(CU)	7440-50-8		51.553	mg	986547	468664
				supplier	alloy	Iron(Fe)	7439-89-6		0.052	mg	995	473
				supplier	alloy	Iron Phosphide(FeP)	26508-33-8		0.015	mg	287	136
				supplier	metallization	Silver(Ag)	7440-22-4		0.636	mg	12171	5782
Soft solder	Other organic materials	1.335	mg	supplier	Soft solder	Silver(Ag)	7440-22-4		0.034	mg	25468	309
				supplier	Soft solder	Tin(Sn)	7440-31-5		0.027	mg	20225	245
				JIG - R	Lead/Lead Compounds	Lead (Pb)	7439-92-1	7a-Lead in high me	1.274	mg	954307	11582
Bonding wires	Other organic materials	0.047	mg	supplier	Bonding wire	Copper(Cu)	7440-50-8		0.047	mg	1000000	427
				supplier	Molding compound	Silica Fused	60676-86-0		47.810	mg	879993	434636
Encapsulation	Other organic materials	54.330	mg	supplier	Molding compound	Epoxy,Cresol Novolac	29690-82-2		0.815	mg	15001	7409
				supplier	Molding compound	Phenol Resin	Proprietary		2.716	mg	49991	24691
				supplier	Molding compound	Epoxy Resin	25068-38-6		2.717	mg	50009	24700
				supplier	Molding compound	Carbon Black	1333-86-4		0.272	mg	5006	2473
Connections coating	Solder	0.926	mg	supplier	Connections coating	Tin(Sn)	7440-31-5		0.926	mg	1000000	8418